imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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Panasonic

Zener Diode DZ2S043×0L

DZ2S043×0L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ2J043 in SSMini2 type package

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 9J or 9U

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C							
Parameter	Symbol	Rating	Unit				
Repetitive peak forward current	IFRM	200	mA				
Total power dissipation *1	PT	150	mW				
Electrostatic discharge ^{*2}	ESD	±15	kV				
Junction temperature	Tj	150	°C				
Operating ambient temperature	Topr	-40 to +85	°C				
Storage temperature	Teta	-55 to +150	ŝ				

 Storage temperature
 Tstg
 -55
 to
 +150
 °C

 Note)
 *1
 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm)
 Solder in (0.8 mm × 0.6 mm)

*2 Test method : IEC61000_4_2

(C = 150 pF, R = 330 Ω , Contact discharge : 10 times)



	± 3 ℃					
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	4.09		4.52	V
Zener operating resistance	RZ	IZ = 5 mA			130	Ω
Reverse current	IR	VR = 1 V			10	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		-0.9		mV/°C

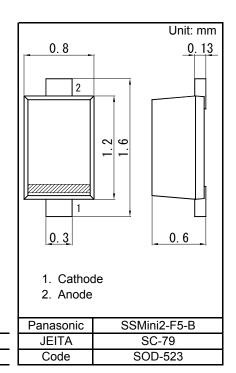
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

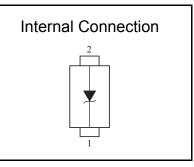
2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 °C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 $^\circ$ C).

*2 VZ guaranted 20 ms after current flow	Rank classification		
*3 Tj = 25 °C to 150 °C	Code M 0	0	
	Rank M No-rank	No-rank	
	VZ 4.18 to 4.40 4.09 to 4.52	2	
	Marking symbol 9U 9J	9J	
		_	

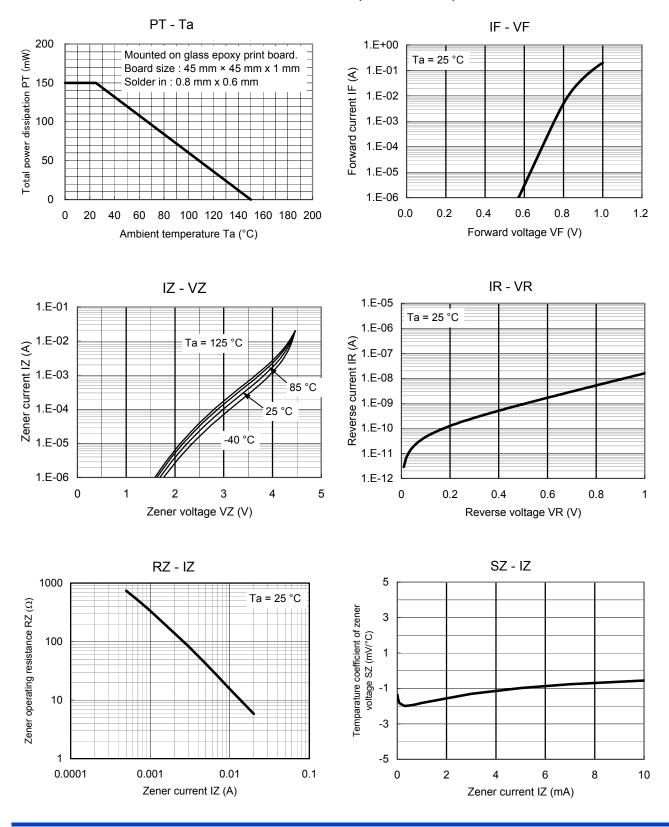






Zener Diode DZ2S043×0L

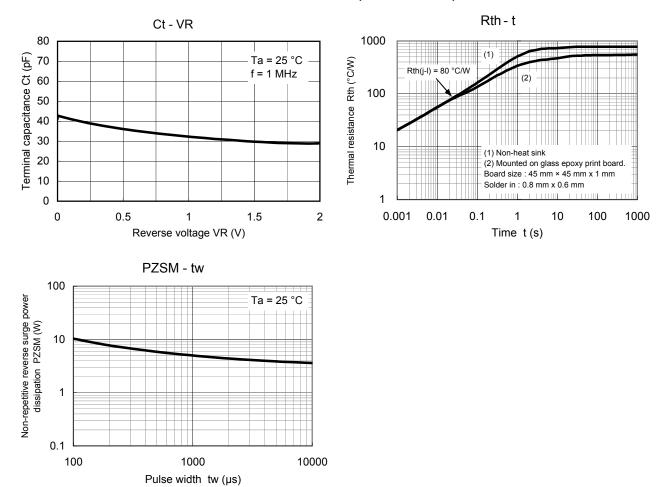
Technical Data (reference)

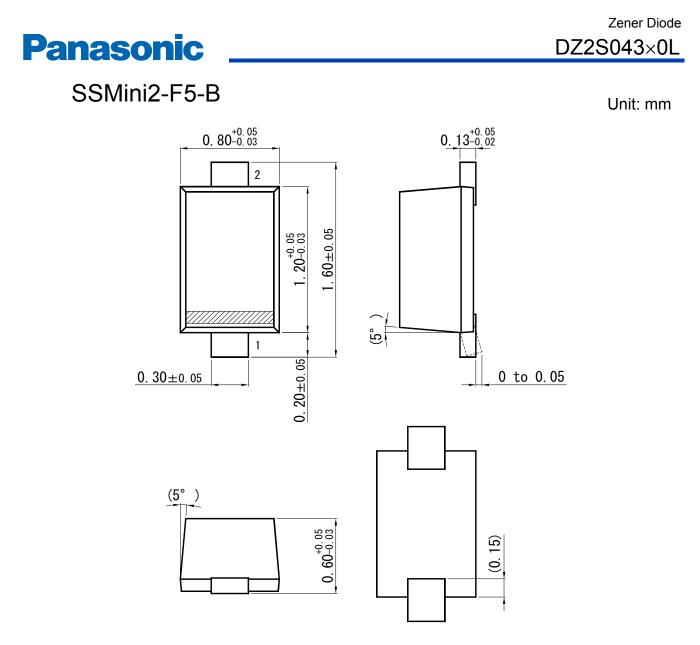


Established : 2009-11-09 Revised : 2013-07-22 **Panasonic**

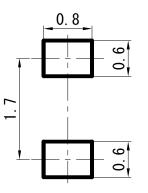


Technical Data (reference)





Land Pattern (Reference) (Unit: mm)



Established : 2009-11-09 Revised : 2013-07-22

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